Lattice Semiconductor Corporation - LFXP3E-4TN144I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	100
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3e-4tn144i

Introduction

The LatticeXP family of FPGA devices combine logic gates, embedded memory and high performance I/Os in a single architecture that is both non-volatile and infinitely reconfigurable to support cost-effective system designs.

The re-programmable non-volatile technology used in the LatticeXP family is the next generation ispXP™ technology. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. In addition, instant-on capability allows for easy interfacing in many applications.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeXP family of FPGA devices. Synthesis library support for LatticeXP is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeXP device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeXP family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further discussion of this topic, see the DDR memory section of this data sheet.

Figure 2-20. Input Register Diagram

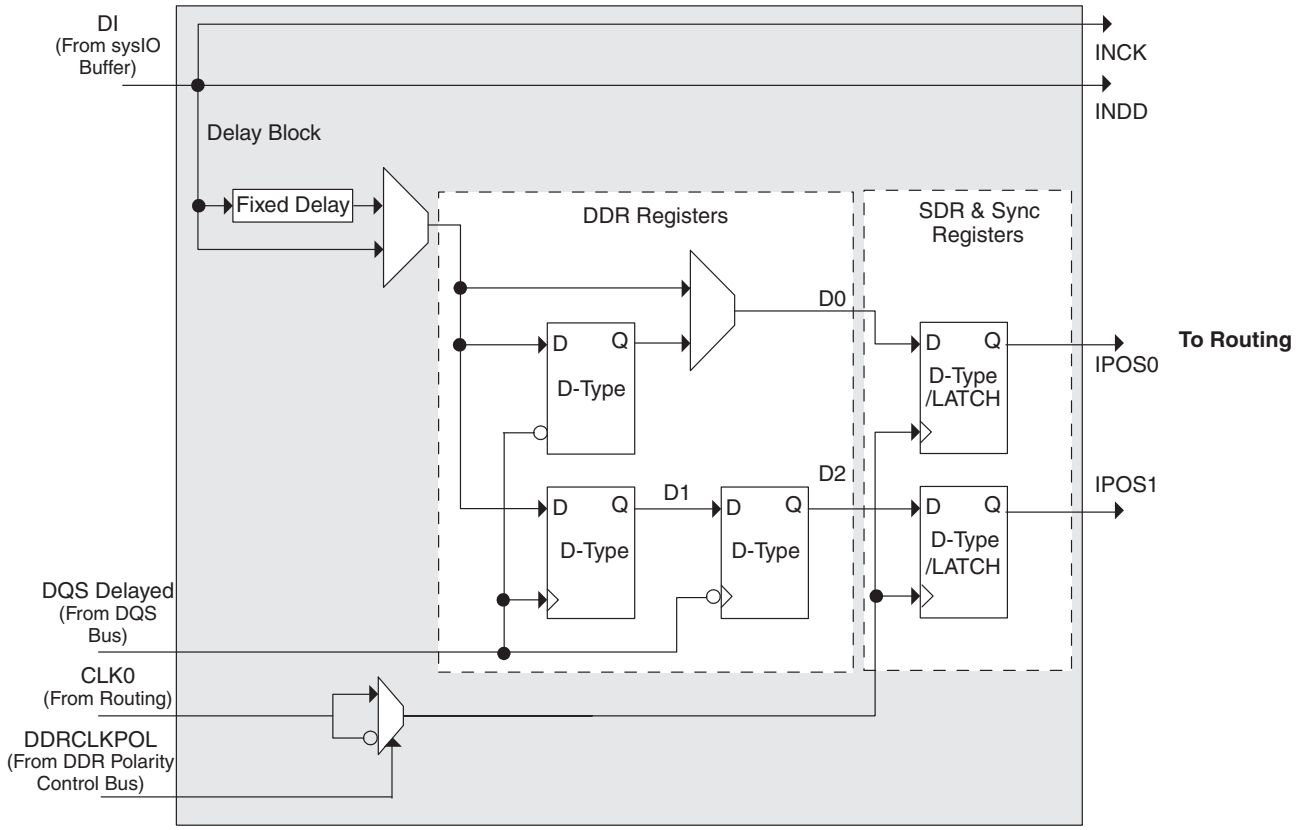


Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

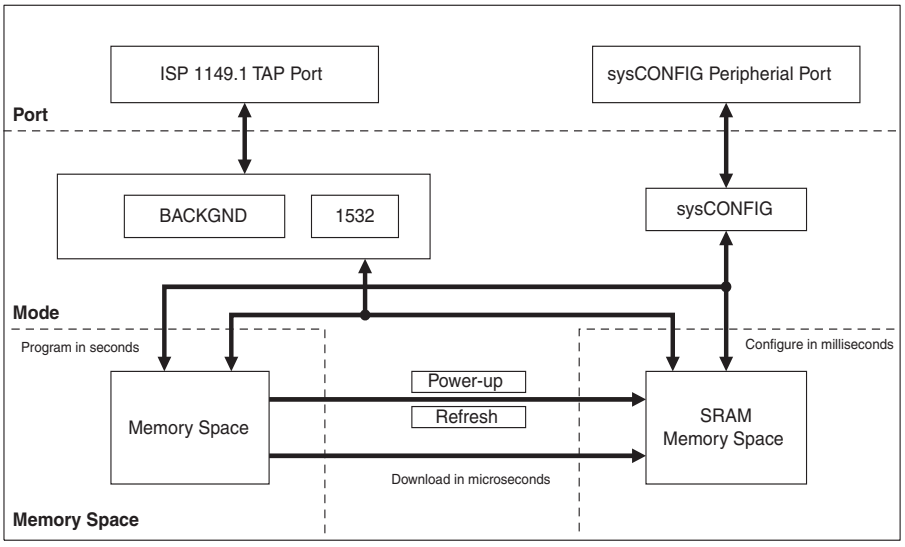
Leave Alone I/O
When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology,* for details.

Security
The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

master serial clock is 2.5MHz. Table 2-10 lists all the available Master Serial Clock frequencies. When a different Master Serial Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Serial Clock frequency for configuration.
2. During configuration the device starts with the default (2.5MHz) Master Serial Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Serial Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information on the use of this oscillator for configuration, please see details of additional technical documentation at the end of this data sheet.

Table 2-10. Selectable Master Serial Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5[1]	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

1. Default

Density Shifting

The LatticeXP family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

LatticeXP Family Data Sheet DC and Switching Characteristics

November 2007 Data Sheet DS1001

Absolute Maximum Ratings[1, 2, 3, 4]

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied[5]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied [5]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[3]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[4]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}.
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/µs during power up when transitioning between 0V and 3.3V.

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sysIO Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	V_{THD}/2	1.2	1.8	V
		200mV ≤ V_{THD}	V_{THD}/2	1.2	1.9	V
		350mV ≤ V_{THD}	V_{THD}/2	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

LatticeXP Internal Timing Parameters[1]

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 Delay (A to D Inputs to F Output)	—	0.28	—	0.34	—	0.40	ns
t_{LUT6_PFU}	LUT6 Delay (A to D Inputs to OFX Output)	—	0.44	—	0.53	—	0.63	ns
t_{LSR_PFU}	Set/Reset to Output of PFU	—	0.90	—	1.08	—	1.29	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) Input Setup Time	0.13	—	0.15	—	0.19	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) Input Hold Time	-0.04	—	-0.03	—	-0.03	—	ns
t_{SUD_PFU}	Clock to D Input Setup Time	0.13	—	0.16	—	0.19	—	ns
t_{HD_PFU}	Clock to D Input Hold Time	-0.03	—	-0.02	—	-0.02	—	ns
t_{CK2Q_PFU}	Clock to Q Delay, D-type Register Configuration	—	0.40	—	0.48	—	0.58	ns
t_{LE2Q_PFU}	Clock to Q Delay Latch Configuration	—	0.53	—	0.64	—	0.76	ns
t_{LD2Q_PFU}	D to Q Throughput Delay when Latch is Enabled	—	0.55	—	0.66	—	0.79	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.58	ns
t_{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.14	—	-0.11	—	ns
t_{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.40	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.37	—	-0.30	—	ns
t_{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	1.02	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.17	—	-0.14	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.48	—	ns
PIC Timing								
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.62	—	0.72	—	0.85	ns
t_{OUT_PIO}	Output Buffer Delay	—	2.12	—	2.54	—	3.05	ns
IOLOGIC Input/Output Timing								
t_{SUI_PIO}	Input Register Setup Time (Data Before Clock)	1.35	—	1.83	—	2.37	—	ns
t_{HI_PIO}	Input Register Hold Time (Data After Clock)	0.05	—	0.05	—	0.05	—	ns
t_{COO_PIO}	Output Register Clock to Output Delay	—	0.36	—	0.44	—	0.52	ns
t_{SUCE_PIO}	Input Register Clock Enable Setup Time	-0.09	—	-0.07	—	-0.06	—	ns
t_{HCE_PIO}	Input Register Clock Enable Hold Time	0.13	—	0.16	—	0.19	—	ns
t_{SULSR_PIO}	Set/Reset Setup Time	0.19	—	0.23	—	0.28	—	ns
t_{HLSR_PIO}	Set/Reset Hold Time	-0.14	—	-0.11	—	-0.09	—	ns
EBR Timing								
t_{CO_EBR}	Clock to Output from Address or Data	—	4.01	—	4.81	—	5.78	ns
t_{COO_EBR}	Clock to Output from EBR Output Register	—	0.81	—	0.97	—	1.17	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.13	—	-0.11	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.37	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.28	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.10	—	-0.08	—	ns

LatticeXP Family Timing Adders[1]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.5	0.5	0.5	ns
LVDS25	LVDS	0.4	0.4	0.4	ns
BLVDS25	BLVDS	0.5	0.5	0.5	ns
LVPECL33	LVPECL	0.6	0.6	0.6	ns
HSTL18_I	HSTL_18 class I	0.4	0.4	0.4	ns
HSTL18_II	HSTL_18 class II	0.4	0.4	0.4	ns
HSTL18_III	HSTL_18 class III	0.4	0.4	0.4	ns
HSTL18D_I	Differential HSTL 18 class I	0.4	0.4	0.4	ns
HSTL18D_II	Differential HSTL 18 class II	0.4	0.4	0.4	ns
HSTL18D_III	Differential HSTL 18 class III	0.4	0.4	0.4	ns
HSTL15_I	HSTL_15 class I	0.5	0.5	0.5	ns
HSTL15_III	HSTL_15 class III	0.5	0.5	0.5	ns
HSTL15D_I	Differential HSTL 15 class I	0.5	0.5	0.5	ns
HSTL15D_III	Differential HSTL 15 class III	0.5	0.5	0.5	ns
SSTL33_I	SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33_II	SSTL_3 class II	0.6	0.6	0.6	ns
SSTL33D_I	Differential SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33D_II	Differential SSTL_3 class II	0.6	0.6	0.6	ns
SSTL25_I	SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25_II	SSTL_2 class II	0.5	0.5	0.5	ns
SSTL25D_I	Differential SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25D_II	Differential SSTL_2 class II	0.5	0.5	0.5	ns
SSTL18_I	SSTL_18 class I	0.5	0.5	0.5	ns
SSTL18D_I	Differential SSTL_18 class I	0.5	0.5	0.5	ns
LVTTL33	LVTTL	0.2	0.2	0.2	ns
LVCMOS33	LVCMOS 3.3	0.2	0.2	0.2	ns
LVCMOS25	LVCMOS 2.5	0.0	0.0	0.0	ns
LVCMOS18	LVCMOS 1.8	0.1	0.1	0.1	ns
LVCMOS15	LVCMOS 1.5	0.1	0.1	0.1	ns
LVCMOS12	LVCMOS 1.2	0.1	0.1	0.1	ns
PCI33	PCI	0.2	0.2	0.2	ns
Output Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.3	0.3	0.3	ns
LVDS25	LVDS 2.5	0.3	0.3	0.3	ns
BLVDS25	BLVDS 2.5	0.3	0.3	0.3	ns
LVPECL33	LVPECL 3.3	0.1	0.1	0.1	ns
HSTL18_I	HSTL_18 class I	0.1	0.1	0.1	ns
HSTL18_II	HSTL_18 class II	0.1	0.1	0.1	ns
HSTL18_III	HSTL_18 class III	0.2	0.2	0.2	ns
HSTL18D_I	Differential HSTL 18 class I	0.1	0.1	0.1	ns
HSTL18D_II	Differential HSTL 18 class II	-0.1	-0.1	-0.1	ns
HSTL18D_III	Differential HSTL 18 class III	0.2	0.2	0.2	ns

Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V_{CCJ}	—	V_{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN[2]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ When driven low, the device moves into Sleep Mode after a specified time.This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.
TOE[3]	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.

1. Applies toþ LFXP10, LFXP15 and LFXP20 only.
2. Applies to LFXP “C” devices only.
3. Applies to LFXP “E” devices only.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
1	PROGRAMN	7	-	-	PROGRAMN	7	-	-
2	CCLK	7	-	-	CCLK	7	-	-
3	GND	-	-	-	GND	-	-	-
4	PL2A	7	T[3]	-	PL2A	7	T[3]	-
5	PL2B	7	C[3]	-	PL2B	7	C[3]	-
6	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
7	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
8	VCCIO7	7	-	-	VCCIO7	7	-	-
9	PL5A	7	-	VREF1_7	PL5A	7	-	VREF1_7
10	PL6B	7	-	VREF2_7	PL6B	7	-	VREF2_7
11	GNDIO7	7	-	-	GNDIO7	7	-	-
12	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
13	PL7B	7	C[3]	-	PL7B	7	C[3]	-
14	VCC	-	-	-	VCC	-	-	-
15	PL8A	7	T	LUM0_PLLT_IN_A	PL8A	7	T	LUM0_PLLT_IN_A
16	PL8B	7	C	LUM0_PLLC_IN_A	PL8B	7	C	LUM0_PLLC_IN_A
17	PL9A	7	T[3]	-	PL9A	7	T[3]	-
18	PL9B	7	C[3]	-	PL9B	7	C[3]	-
19	VCCP0	-	-	-	VCCP0	-	-	-
20	GNDP0	-	-	-	GNDP0	-	-	-
21	VCCIO6	6	-	-	VCCIO6	6	-	-
22	PL11A	6	T[3]	-	PL16A	6	T[3]	-
23	PL11B	6	C[3]	-	PL16B	6	C[3]	-
24	PL12A	6	T	PCLKT6_0	PL17A	6	T	PCLKT6_0
25	PL12B	6	C	PCLKC6_0	PL17B	6	C	PCLKC6_0
26	PL13A	6	T[3]	-	PL18A	6	T[3]	-
27	PL13B	6	C[3]	-	PL18B	6	C[3]	-
28	GNDIO6	6	-	-	GNDIO6	6	-	-
29	PL14A	6	-	VREF1_6	PL22A	6	-	VREF1_6
30	PL15B	6	-	VREF2_6	PL23B	6	-	VREF2_6
31	PL16A	6	T[3]	DQS	PL24A	6	T[3]	DQS
32	PL16B	6	C[3]	-	PL24B	6	C[3]	-
33	PL17A	6	-	-	PL25A	6	-	-
34	PL18A	6	T[3]	-	PL26A	6	T[3]	-
35	PL18B	6	C[3]	-	PL26B	6	C[3]	-
36	VCCAUX	-	-	-	VCCAUX	-	-	-
37	SLEEPN[1]/TOE[2]	-	-	-	SLEEPN[1]/TOE[2]	-	-	-
38	INITN	5	-	-	INITN	5	-	-
39	VCC	-	-	-	VCC	-	-	-
40	PB2B	5	-	VREF1_5	PB5B	5	-	VREF1_5
41	PB5B	5	-	VREF2_5	PB8B	5	-	VREF2_5
42	PB7A	5	T	-	PB10A	5	T	-
43	PB7B	5	C	-	PB10B	5	C	-
44	GNDIO5	5	-	-	GNDIO5	5	-	-
45	PB9A	5	-	-	PB12A	5	-	-
46	PB10B	5	-	-	PB13B	5	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT31B	1	C	-	PT35B	1	C	-
B15	PT31A	1	T	-	PT35A	1	T	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT28A	1	-	VREF1_1	PT34B	1	C	VREF1_1
C11	PT30A	1	T	DQS	PT34A	1	T	DQS
A14	PT29B	1	-	-	PT33B	1	-	-
B13	PT30B	1	C	-	PT32A	1	-	-
F12	PT27B	1	C	-	PT31B	1	C	-
E11	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	-	PT30B	1	C	-
C13	PT26A	1	T	D0	PT30A	1	T	D0
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C10	PT25B	1	C	D1	PT29B	1	C	D1
E10	PT25A	1	T	VREF2_1	PT29A	1	T	VREF2_1
A12	PT24B	1	C	-	PT28B	1	C	-
B12	PT24A	1	T	D2	PT28A	1	T	D2
C12	PT23B	1	C	D3	PT27B	1	C	D3
A11	PT23A	1	T	-	PT27A	1	T	-
B11	PT22B	1	C	-	PT26B	1	C	-
D11	PT22A	1	T	DQS	PT26A	1	T	DQS
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B9	PT21B	1	-	-	PT25B	1	-	-
D9	PT20A	1	-	D4	PT24A	1	-	D4
A10	PT19B	1	C	-	PT23B	1	C	-
B10	PT19A	1	T	D5	PT23A	1	T	D5
D10	PT18B	1	C	D6	PT22B	1	C	D6
A9	PT18A	1	T	-	PT22A	1	T	-
C9	PT17B	1	C	D7	PT21B	1	C	D7
C8	PT17A	1	T	-	PT21A	1	T	-
E9	PT16B	0	C	BUSY	PT20B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B8	PT16A	0	T	CS1N	PT20A	0	T	CS1N
A8	PT15B	0	C	PCLKC0_0	PT19B	0	C	PCLKC0_0
A7	PT15A	0	T	PCLKT0_0	PT19A	0	T	PCLKT0_0
B7	PT14B	0	C	-	PT18B	0	C	-
C7	PT14A	0	T	DQS	PT18A	0	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F15	PR10B	2	-	-	PR10B	2	-	-
E15	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
F14	PR8B	2	C[3]	-	PR8B	2	C[3]	-
E14	PR8A	2	T[3]	-	PR8A	2	T[3]	-
D15	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
C15	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
-	GNDIO2	2	-	-	GNDIO2	2	-	-
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT40B	1	C	-	PT44B	1	C	-
B15	PT40A	1	T	-	PT44A	1	T	-
D12	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C11	PT39A	1	T	DQS	PT43A	1	T	DQS
A14	PT38B	1	-	-	PT42B	1	-	-
B13	PT37A	1	-	-	PT41A	1	-	-
F12	PT36B	1	C	-	PT40B	1	C	-
E11	PT36A	1	T	-	PT40A	1	T	-
A13	PT35B	1	C	-	PT39B	1	C	-
C13	PT35A	1	T	D0	PT39A	1	T	D0
C10	PT34B	1	C	D1	PT38B	1	C	D1
E10	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
A12	PT33B	1	C	-	PT37B	1	C	-
B12	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C12	PT32B	1	C	D3	PT36B	1	C	D3
A11	PT32A	1	T	-	PT36A	1	T	-
B11	PT31B	1	C	-	PT35B	1	C	-
D11	PT31A	1	T	DQS	PT35A	1	T	DQS
B9	PT30B	1	-	-	PT34B	1	-	-
D9	PT29A	1	-	D4	PT33A	1	-	D4
A10	PT28B	1	C	-	PT32B	1	C	-
B10	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D10	PT27B	1	C	D6	PT31B	1	C	D6

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
A7	PT13A	0	T	DI	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT12B	0	C	-	PT17B	0	C	-	PT21B	0	C	-
C6	PT12A	0	T	CSN	PT17A	0	T	CSN	PT21A	0	T	CSN
C10	PT11B	0	C	-	PT16B	0	C	-	PT20B	0	C	-
C9	PT11A	0	T	-	PT16A	0	T	-	PT20A	0	T	-
A6	PT10B	0	C	VREF2_0	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
B6	PT10A	0	T	DQS	PT15A	0	T	DQS	PT19A	0	T	DQS
A5	PT9B	0	-	-	PT14B	0	-	-	PT18B	0	-	-
B5	PT8A	0	-	-	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT7B	0	C	-	PT12B	0	C	-	PT16B	0	C	-
A4	PT7A	0	T	-	PT12A	0	T	-	PT16A	0	T	-
D9	PT6B	0	C	-	PT11B	0	C	-	PT15B	0	C	-
D8	PT6A	0	T	-	PT11A	0	T	-	PT15A	0	T	-
B4	PT5B	0	C	-	PT10B	0	C	-	PT14B	0	C	-
A2	PT5A	0	T	-	PT10A	0	T	-	PT14A	0	T	-
A3	PT4B	0	C	-	PT9B	0	C	-	PT13B	0	C	-
B3	PT4A	0	T	-	PT9A	0	T	-	PT13A	0	T	-
C4	PT3B	0	C	-	PT8B	0	C	-	PT12B	0	C	-
C3	PT3A	0	T	-	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C2	-	-	-	-	PT7B	0	C	-	PT11B	0	C	-
D3	PT2A	0	-	-	PT7A	0	T	DQS	PT11A	0	T	DQS
D7	-	-	-	-	PT6B	0	-	-	PT10B	0	-	-
D6	-	-	-	-	PT5A	0	-	-	PT9A	0	-	-
E4	-	-	-	-	PT4B	0	C	-	PT8B	0	C	-
D4	-	-	-	-	PT4A	0	T	-	PT8A	0	T	-
D5	-	-	-	-	PT3B	0	-	-	PT7B	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C1	CFG0	0	-	-	CFG0	0	-	-	CFG0	0	-	-
B2	CFG1	0	-	-	CFG1	0	-	-	CFG1	0	-	-
B1	DONE	0	-	-	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-	GND	-	-	-
H11	GND	-	-	-	GND	-	-	-	GND	-	-	-
H12	GND	-	-	-	GND	-	-	-	GND	-	-	-
H13	GND	-	-	-	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-	GND	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L1	-	-	-	-	PL23A	7	T[3]	-
M1	-	-	-	-	PL23B	7	C[3]	-
M2	-	-	-	-	PL24A	7	-	-
L5	VCCP0	-	-	-	VCCP0	-	-	-
N2	GNDP0	-	-	-	GNDP0	-	-	-
N1	-	-	-	-	PL25B	6	-	-
P2	-	-	-	-	PL26A	6	T[3]	-
P1	-	-	-	-	PL26B	6	C[3]	-
M4	PL23A	6	T[3]	-	PL27A	6	T[3]	-
M3	PL23B	6	C[3]	-	PL27B	6	C[3]	-
R2	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
R1	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
N3	PL25A	6	T[3]	-	PL29A	6	T[3]	-
N4	PL25B	6	C[3]	-	PL29B	6	C[3]	-
M5	PL26A	6	-	-	PL30A	6	-	-
N5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T2	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
T1	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U2	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
U1	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
P3	PL30A	6	T[3]	-	PL34A	6	T[3]	-
P4	PL30B	6	C[3]	-	PL34B	6	C[3]	-
P6	PL32A	6	T[3]	-	PL36A	6	T[3]	-
P5	PL32B	6	C[3]	-	PL36B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
V2	PL33A	6	T	-	PL37A	6	T	-
V1	PL33B	6	C	-	PL37B	6	C	-
W2	PL34A	6	T[3]	-	PL38A	6	T[3]	-
W1	PL34B	6	C[3]	-	PL38B	6	C[3]	-
R3	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL36B	6	-	-	PL40B	6	-	-
R6	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
R5	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
Y2	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
Y1	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
T3	PL39A	6	T[3]	-	PL43A	6	T[3]	-
T4	PL39B	6	C[3]	-	PL43B	6	C[3]	-
W3	PL40A	6	T[3]	-	PL44A	6	T[3]	-
V3	PL40B	6	C[3]	-	PL44B	6	C[3]	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R18	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
R17	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
Y22	PR37B	3	C[3]	-	PR41B	3	C[3]	-
Y21	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
W22	PR36B	3	-	-	PR40B	3	-	-
W21	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
P17	PR34B	3	C[3]	-	PR38B	3	C[3]	-
P18	PR34A	3	T[3]	-	PR38A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
R19	PR33B	3	C	-	PR37B	3	C	-
R20	PR33A	3	T	-	PR37A	3	T	-
V22	PR32B	3	C[3]	-	PR36B	3	C[3]	-
V21	PR32A	3	T[3]	-	PR36A	3	T[3]	-
U22	PR30B	3	C[3]	-	PR34B	3	C[3]	-
U21	PR30A	3	T[3]	-	PR34A	3	T[3]	-
P19	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
P20	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
T22	PR28B	3	C[3]	-	PR32B	3	C[3]	-
T21	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
R22	PR27B	3	-	-	PR31B	3	-	-
R21	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
N19	PR25B	3	C[3]	-	PR29B	3	C[3]	-
N20	PR25A	3	T[3]	-	PR29A	3	T[3]	-
N18	PR24B	3	C	-	PR28B	3	C	-
M18	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P22	PR23B	3	C[3]	-	PR27B	3	C[3]	-
P21	PR23A	3	T[3]	-	PR27A	3	T[3]	-
N22	-	-	-	-	PR26B	3	C[3]	-
N21	-	-	-	-	PR26A	3	T[3]	-
M19	-	-	-	-	PR25B	3	-	-
M20	GNDP1	-	-	-	GNDP1	-	-	-
L18	VCCP1	-	-	-	VCCP1	-	-	-
M21	-	-	-	-	PR24A	2	-	-
M22	PR22B	2	C[3]	-	PR23B	2	C[3]	-
L22	PR22A	2	T[3]	-	PR23A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
L19	-	-	-	-	PR22B	2	C[3]	-
L20	-	-	-	-	PR22A	2	T[3]	-
L21	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K22	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0

LatticeXP Family Data Sheet Ordering Information

December 2005 Data Sheet DS1001

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

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Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484C	300	1.8/2.5/3.3V	-3	fpBGA	484	COM	15.5K
LFXP15C-4F484C	300	1.8/2.5/3.3V	-4	fpBGA	484	COM	15.5K
LFXP15C-5F484C	300	1.8/2.5/3.3V	-5	fpBGA	484	COM	15.5K
LFXP15C-3F388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	15.5K
LFXP15C-4F388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	15.5K
LFXP15C-5F388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	15.5K
LFXP15C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	15.5K
LFXP15C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	15.5K
LFXP15C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4F484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5F484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3F388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4F388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5F388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4Q208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5Q208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3T144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4T144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5T144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3T100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4T100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5T100C	62	1.2V	-5	TQFP	100	COM	3.1K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4F484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4F484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4Q208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3T144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4T144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3T100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4T100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4F256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3Q208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4Q208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3T144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4T144I	100	1.2V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4F388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3F256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4F256I	188	1.2V	-4	fpBGA	256	IND	9.7K